

Cobalt-Plated Copper Foil

Catlog Number: BMBCC-0094

• Description

Copper foil with a cobalt surface layer designed to improve the cycle life of silicon-carbon composite anodes.

• Basic Information

Substrate Material: Copper (Core)

Purity (%): ≥ 99.9

Thickness (μm): 15

Width (mm): 200

Areal Density (g/m^2): 135 - 140

Tensile Strength (MPa): ≥ 310

Elongation (%): ≥ 2.5

Surface Finish: Cobalt Plated

Surface Roughness (R_a , μm): ≤ 0.30

Electrical Resistivity ($\Omega\cdot\text{m}$): 2.1×10^{-8}

Thermal Conductivity ($\text{W}/\text{m}\cdot\text{K}$): 360

Melting Point ($^{\circ}\text{C}$): 1083 (Cu)

Oxidation Resistance (Temp/Time): 250°C / 45min

Coating Type: Cobalt (Co)

Coating Thickness (μm): 0.2 - 0.5

Core ID (mm): 76

Standard Length (m): 50

Operating Voltage Range (V): 0.0 - 2.5

Application Compatibility: Si-C Anodes

Storage Requirements: Vacuum Bag

Form Factor: Roll

Hydrophilic Properties: Interface Stability

Compliance / Grade: Research Grade

 For Research or Industrial Raw Materials, Not For Personal Medical Use!